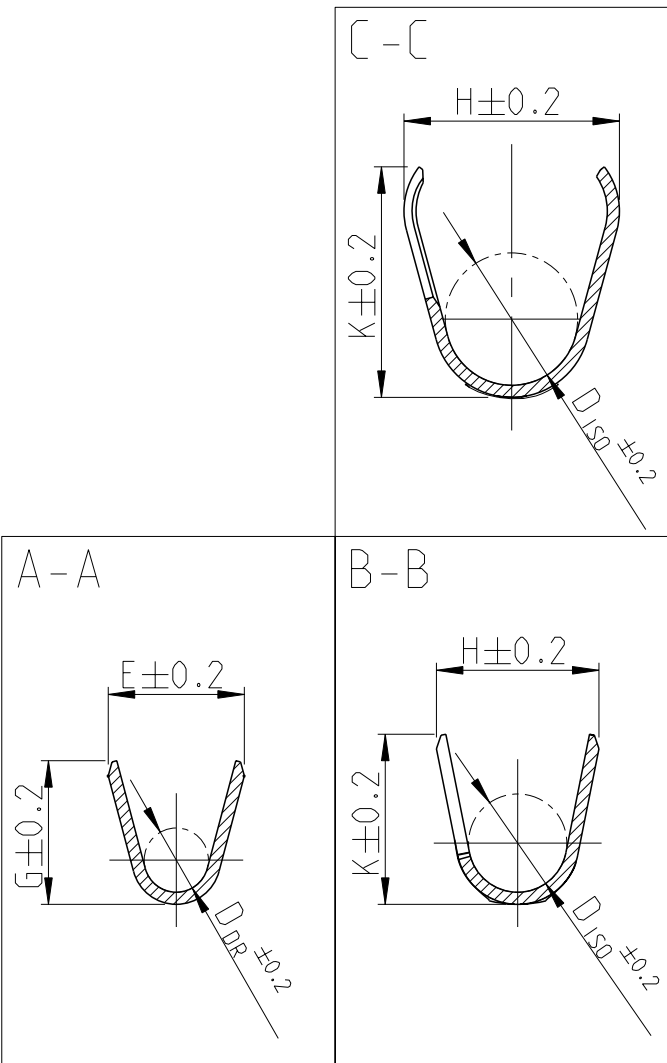
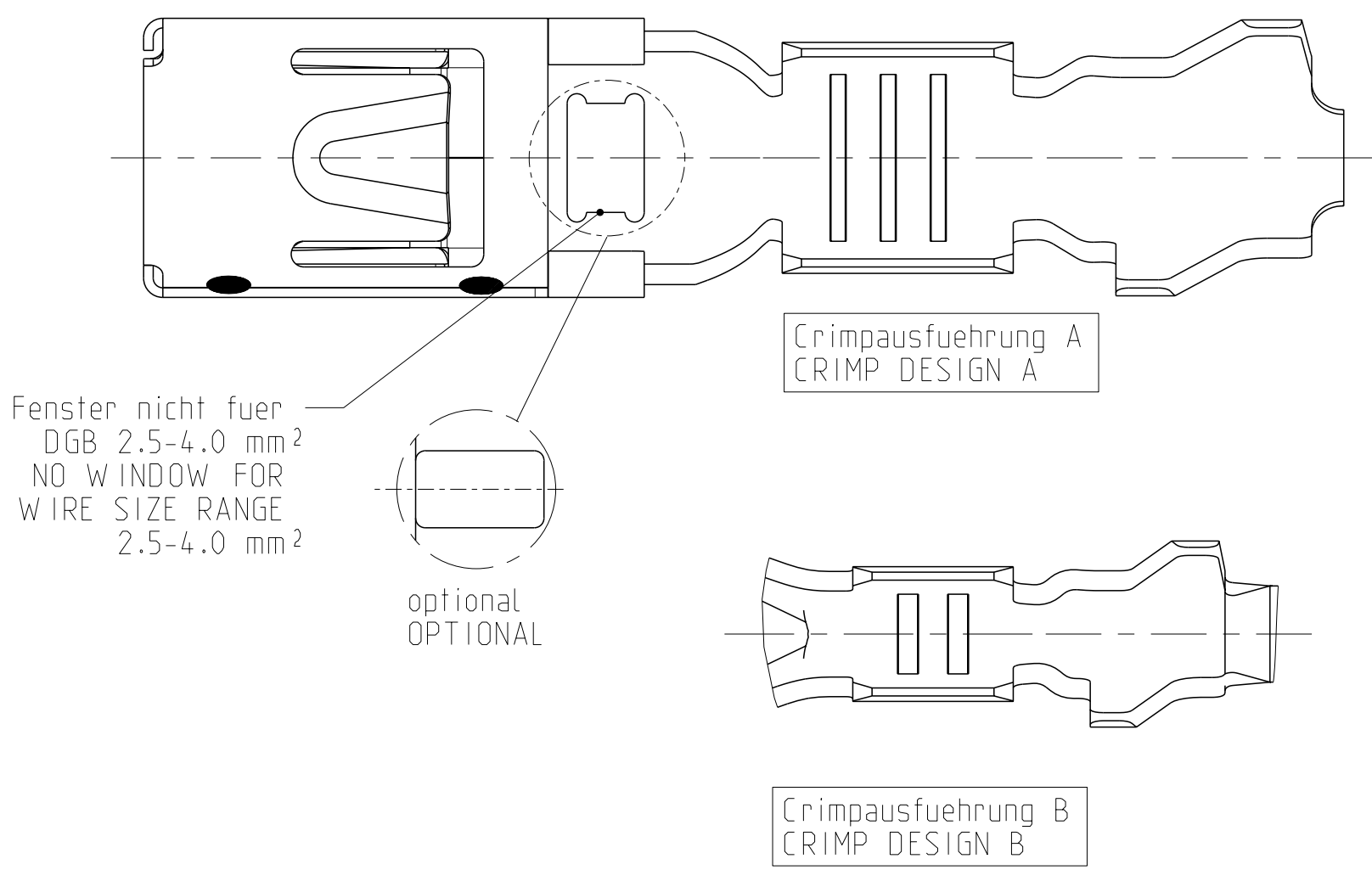
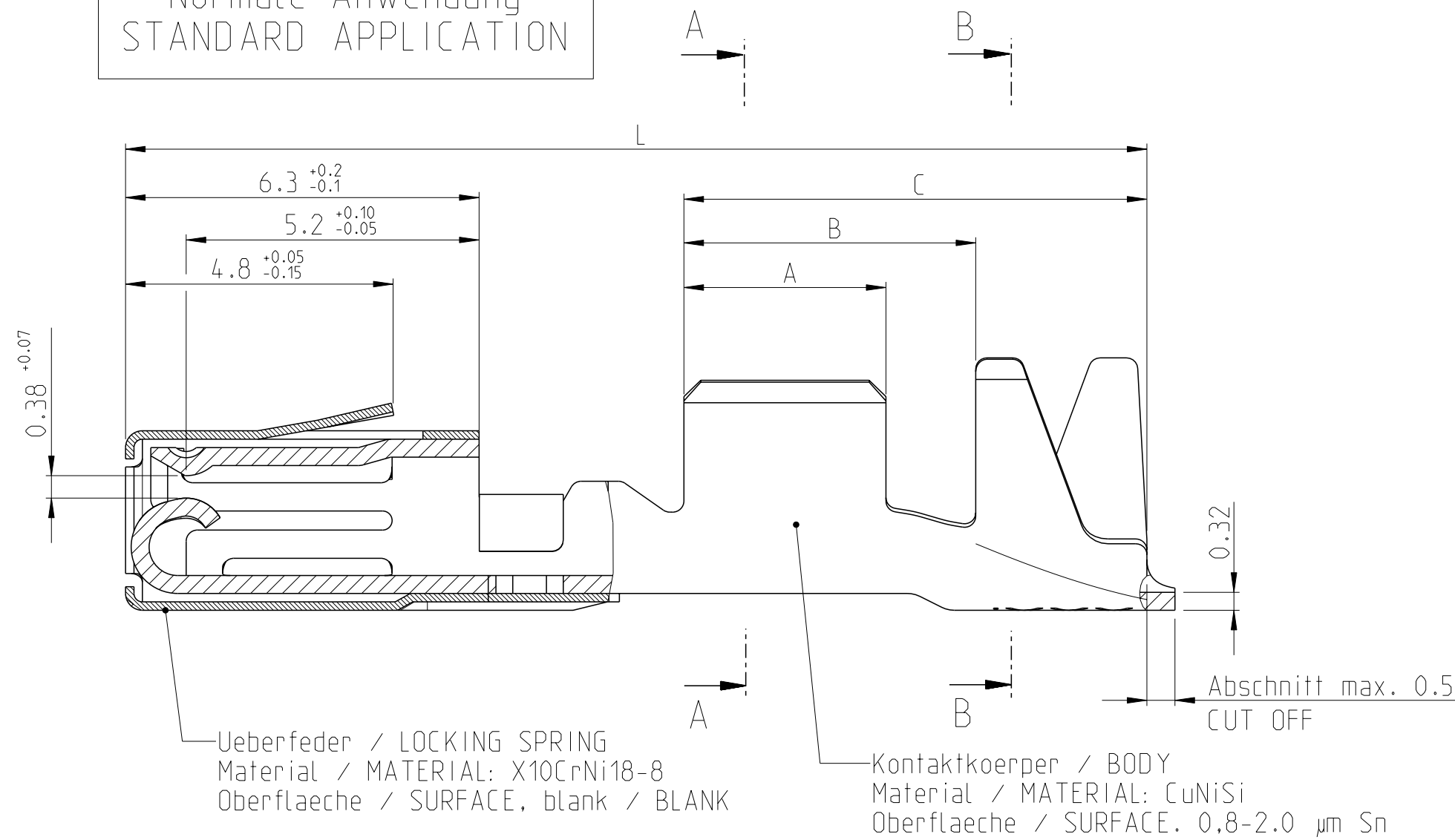
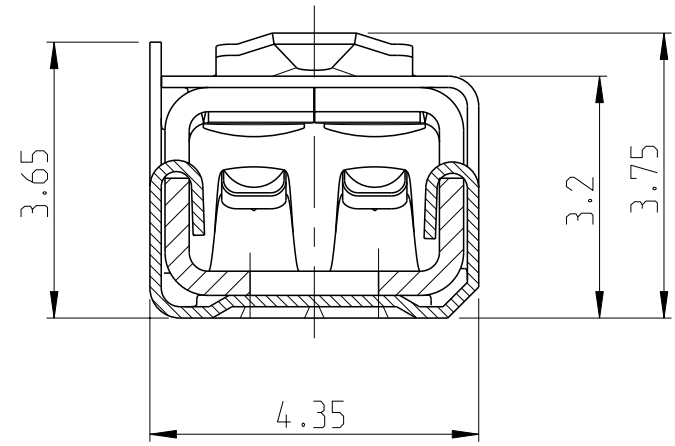


Normale Anwendung
STANDARD APPLICATION

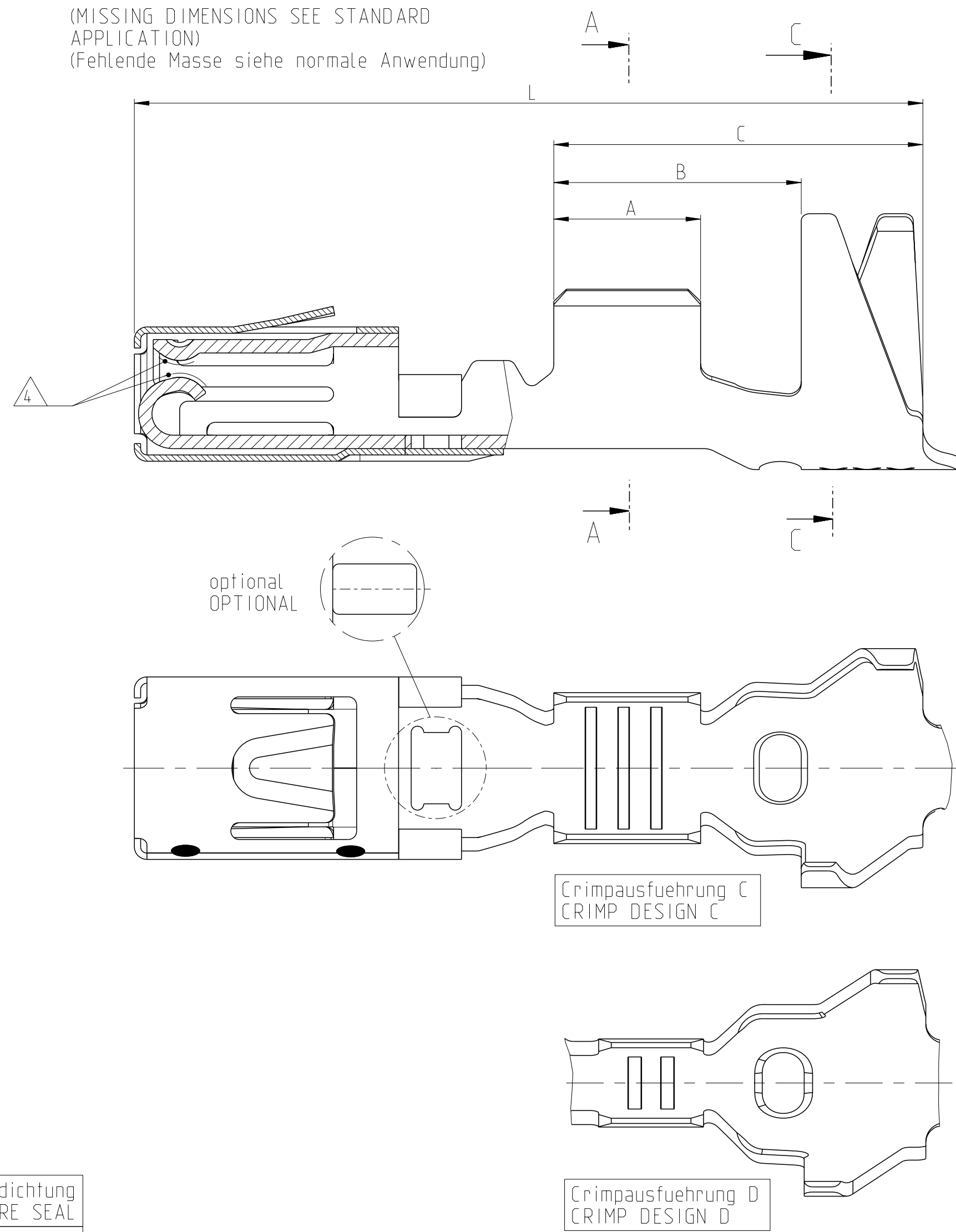


Ansicht ohne Crimp
VIEW WITHOUT CRIMP



Einzel dichtungssystem
SINGLE WIRE SEAL SYSTEM

(MISSING DIMENSIONS SEE STANDARD APPLICATION)
(Fehlende Masse siehe normale Anwendung)



NOTES
Bemerkungen

- SUITABLE FOR PIN CONTACT SEE DRAWING:
Passend zu Stiftkontakt:
TE: 1355933
- FOR FLR-CONDUCTOR ACCORDING TO DIN 72551, PART 6 ONLY
Nur fuer FLR-Leitungen nach DIN 72551, Teil 6
- DETAILS OF DESIGN ARE LEFT TO MANUFACTURER
Einzelheiten der Ausfuehrung bleiben dem Hersteller ueberlassen

MIN. 0.8 µm Au OVER MIN. 1.2 µm Ni
Min. 0.8 µm Au ueber min. 1.2 µm Ni

2-4 µm ELECTROPLATED SILVER
2-4 µm galvanisch Silber

MIN. 0.8 µm PdNi OVER MIN. 1.2 µm Ni
Min. 0.8 µm PdNi ueber min. 1.2 µm Ni

FOR INSPECTION PURPOSES ONLY
Nur fuer Pruefzwecke

MIN. 2.8-5.0 µm Ag OVER MIN. 0.2-1.0 µm Ni
Min. 2.8-5.0 µm Ag ueber min. 0.2-1.0 µm Ni

1:1

1:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN S.Garcia	22MAY2000			NAME MICRO POWER QUADLOK BUCHSENKONTAKT Tabellenzeichnung Buchsenkontakt TABLE SOCKET CONTACT	
DIMENSIONS: mm		CHK R.Jetten	22MAY2000				
TOLERANCES UNLESS OTHERWISE SPECIFIED: DIN 6930-2-mH		PRODUCT SPEC 108-18476-1		SIZE 116-18141-1		RESTRICTED TO REVISION B13	
MATERIAL -		FINISH -		WEIGHT -		SCALE 5:1	
CUSTOMER DRAWING		SHEET 1 OF 1		REVISION B13			